

100a

Figure 1a

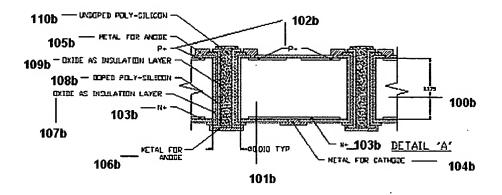


Figure 1b

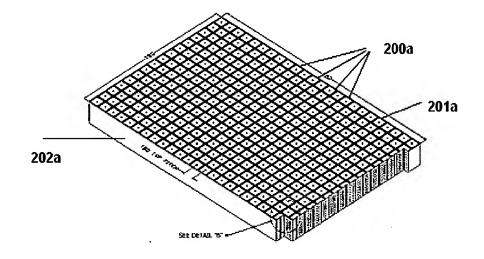


Figure 2a

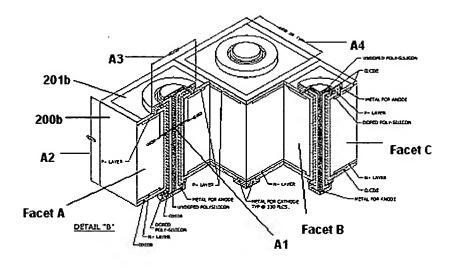


Figure 2b

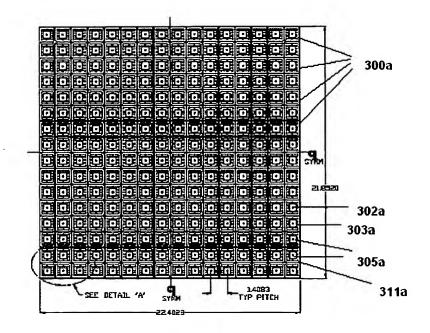


Figure 3a

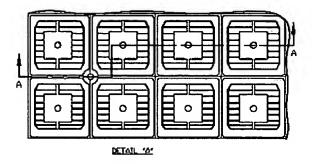


Figure 3b

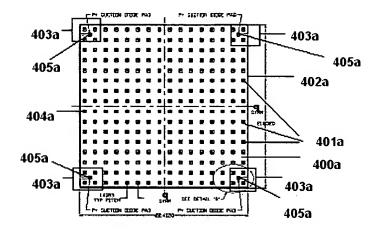


Figure 4a

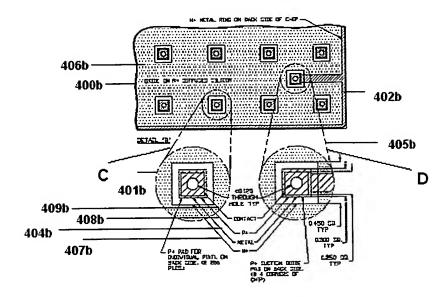


Figure 4b

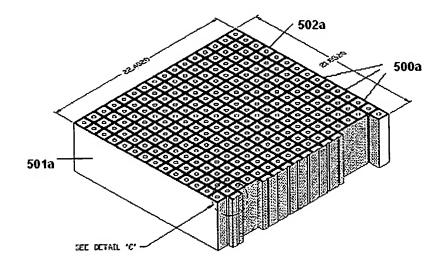


Figure 5a

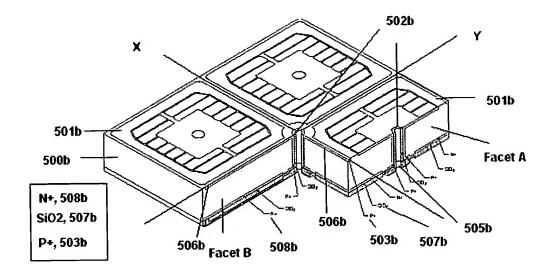


Figure 5b

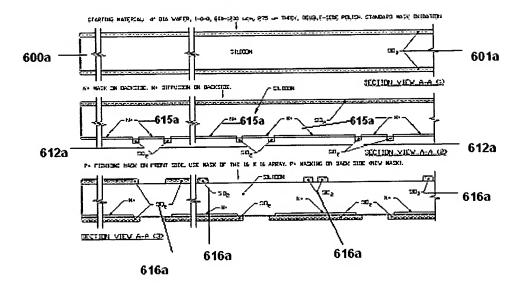


Figure 6a

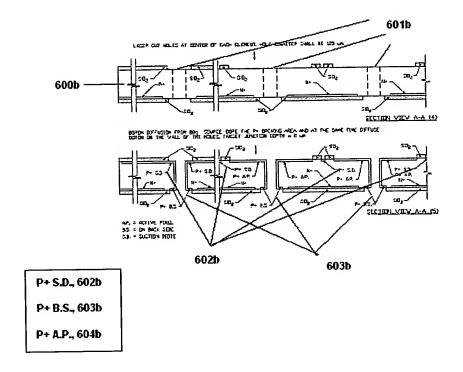
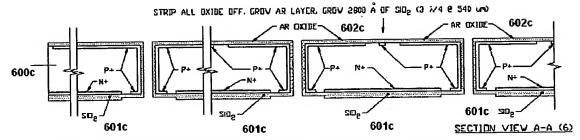


Figure 6b

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CONTACT WINDOW MASKING AND ETCH CONTACT WINDOW DIVIDE ON THE BACK SIDE P+ AND ETCH N+RING AT THE PERIPHERY OF THE CHIP.

NETALIZE THE BACK SIDE OF THE VAFER VITH AL-NI-AU, THEN DO THE METAL MASKING AND ETCH METAL IN THE BACKSIDE.

SECTION VIEW A-A (7)

Figure 6c

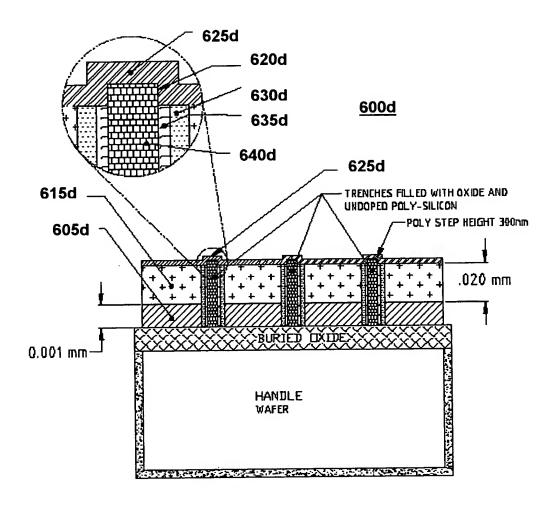


Figure 6d